

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Withdrawn) A substrate for semiconductor apparatus, comprising:  
a substrate main body having a first surface for mounting the semiconductor apparatus, a second surface and a plurality of through-holes;  
at least one contour line formed on at least one surface of the substrate main body, the contour line defining an area on the substrate main body;  
a plurality of leads formed on the first surface, the plurality of leads extending from a peripheral area toward a central area of the substrate main body, portions of the plurality of leads extending into the area defined by the contour line;  
a plurality of conduction sections formed on the second surface, each conduction section defining at least part of an external terminal, the conduction sections being electrically connected to the leads via the plurality of through-holes, internal surfaces of the through-holes are conductive and connected to respective leads; and  
the through-holes are arranged corresponding to the respective leads such that each lead has a through-hole in an area other than the area defined by the contour line and a through-hole in the area defined by the contour line, wherein when the substrate main body is cut along the contour line, the portions of the plurality of leads in the area defined by the contour line and the through-holes connected to the portions of the respective plurality of leads define the conduction sections.
2. (Canceled).
3. (Withdrawn) The substrate for semiconductor apparatus of claim 1, wherein the substrate main body defines a central area and has one through-hole on the side of the central area for each of the leads, and the conduction sections are electrically connected to the leads through the through-holes.

4. (Withdrawn) The substrate for semiconductor apparatus of claim 1, wherein the substrate main body has the plurality of through-holes for each of the leads, and the conduction sections are electrically connected to each corresponding one of the leads through a predetermined one of the through-holes.

5. (Canceled).

6. (Withdrawn) An electronic apparatus having a circuit substrate mounted with the substrate for semiconductor apparatus according to claim 1.

7. (Currently Amended) A semiconductor apparatus, comprising:  
a semiconductor device having a plurality of electrodes;  
a substrate main body having a first surface for mounting the semiconductor device, a second surface and a plurality of through-holes;  
at least one contour line formed on at least one surface of the substrate main body, the contour line defining an area on the substrate main body;  
a plurality of leads formed on the first surface, the plurality of leads extending from a peripheral area toward a central area of the substrate main body, portions of the plurality of leads extending into the area defined by the contour line;  
a plurality of conduction sections formed on the second surface, one of the conduction sections defining an external terminal, the conduction sections being electrically connected to the leads through the plurality of through-holes, internal surfaces of the through-holes are conductive and connected to respective leads; and  
the through-holes are arranged corresponding to the respective leads such that ~~each~~every lead has a through-hole in an area other than the area defined by the contour line and a through-hole in the area defined by the contour line, ~~wherein when the substrate main body is cut along the contour line, the portions of the plurality of leads in the area defined by the contour line and the through-holes of the respective leads define the conduction sections.~~

8. (Canceled).

9. (Currently Amended) The semiconductor apparatus of claim 7, wherein the substrate main body ~~defines a central area and~~ has one through-hole on the side of the central area for each of the leads, and the conduction sections are electrically connected the leads through the through-holes.

10. (Previously Amended) The semiconductor apparatus of claim 7, wherein the substrate main body has the plurality of through-holes for each of the leads, and the conduction sections are electrically connected to each corresponding one of the leads through a predetermined one of the through-holes.

11. (Canceled).

12. (Withdrawn) An electronic apparatus having a circuit substrate mounted with the semiconductor apparatus according to claim 7.

13-25. (Canceled).